## On- and near-detector DAQ work for the EUDET calorimeters



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### Objectives

- Utilise off the shelf technology
  - Minimise cost, leverage industrial knowledge
  - Use standard networking chipsets and protocols, FPGAs etc.
- Design for Scalability
- Make it as generic as possible
  - exception: detector interface to several subdetectors
- Act as a catalyst to use commodity hardware
- ⇒ build a working technical prototype (to verify assembly, mechanical structure) and DAQ system to be used for prototype by 2009

#### EUDET prototype (example AHCAL) 38 layers Typical layer 80000 tiles $2m^2$ 2000 tiles FEE: 32 ASICs (64-fold) 4 readout lines / layer EUDET: Mechanical structure Instrument one tower (e.m. shower size) electronics integration: + 1 layer (few 1000 tiles) DESY and Hamburg U

- 3 different detector types: ECAL, AHCAL, DHCAL
- study of full scale technological solutions

### DAQ architecture

Off Detector Receiver (ODR)

**DAQ** software

Link Data Aggregator (LDA)

Detector Interface (DIF)

**Detector Unit** 



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### DAQ architecture

#### covered in Tao's talk

covered in Valeria's talk



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# Detector Interface (DIF) status

- Two halves Generic DAQ and Specific Detector
  - 3 detectors: ECAL, AHCAL, DHCAL
  - 1 DAQ Interface!
- Transmits configuration data to the Detector Unit and transfers data to downstream DAQ
- Designed with redundancies for readout
- Signal transmission along ECAL test slab and ECAL slab interconnects being tested





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### Detector Interface (DIF) status



- keep DIF simple hence predictable (no local 'memory management', for example)
- DIF proto: large Xilinx FPGA, to be slimmed down for final DIF
- board is delivered

### ECAL slab interconnect

• geometry investigated (multi-rows preferred)



- technology: conductive adhesive vs. flat flexible cable (FFC), with preference to FFC
- soldering technologies are being investigated (Hot-Bar soldering, laser soldering, IR soldering)

## Link Data Aggregator (LDA)

#### Hardware:

- PCBs designed and manufactured
- Carrier BD2 board likely to be constrained to at least a Spartan3 2000 model
- Gigabit links as shown below, 1 Ethernet and a TI TLK chipset
- USB used as a testbench interface when debugging





## Link Data Aggregator (LDA)

#### Firmware:

- Ethernet interface based on Xilinx IP cores
- DIF interface based on custom SERDES with state machines for link control. Self contained, with a design for the DIF partner SERDES as well
- Possible to reuse parts from previous Virtex4 network tests
- No work done on TLK interface as of yet
- 1 Link Data Aggregator can serve 8 Detector Interfaces
- Might not be enough for DHCAL => 2nd prototype will be designed

### Summary

• testbeam for the EUDET module in 2009



prototypes of all hardware components
(Detector Interface, Link Data Aggregator and
Off Detector Receiver) built and tests started
⇒ Debugging and improving of each component before
putting the components together

### Backup slides

## Clock and Control (C&C) board



- C&C unit provides machine clock and fast signals to 8x Off Detector Receiver/Link Data Aggregator.
- Logic control (FPGA, connected via USB)
  - Link Datas Aggregator provides next stage fanout to Detector Interfaces
    - -Eg C&C unit -> 8 LDAs -> 10 DIFs = 80 DUs.
  - Signalling over same HDMI type cabling

 Facility to generate optical link clock (~125-250MHz from ~50MHz machine clock)

#### Board is already designed, will be build soon

### Single Event Upset (SEU) Study

finalised, accepted by NIM



SEU cross section depending or

- FPGA type
- traversing particle  $(n,p,\pi)$
- energy of traversing particle
- => need to study particle spectra

## Single Event Upset (SEU) Study

Main backgrounds: (tt, WW and bhabha scattering also studied)



- $\Rightarrow$  SEU rate of 14 min-12hours depending on FPGA type for the whole ECAL, needs to be taken into account in control software
- $\Rightarrow$  fluence of 2\*10<sup>6</sup>/cm per year, not critical
- $\Rightarrow$  radiation of 0.16Rad/year, not critical
- $\rightarrow$  occurspondy of 0.003/bunch train (not including noise), WB, M.W. UCL